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**Date:** 25 October 2001  
**To:** Assistant Commissioner for Patents  
Attn: Group Art Unit 2811  
Washington DC 20231  
**From:** Haim Melman  
P.O.Box 1341  
Kfar-Saba  
Israel 44113  
**Subject:** Patent application 09/725166, Avner Badehi

Dear Sir.

Searching through USPTO web site I noted patent application 09/725166, Avner Badehi, filed 29 November 2000.

Allow me please to disclose a prior art, US patent 6,134,393, Haim Melman, filed 8 September 1997.

Two reference pages from USPTO site are attached for your convenience.

Sincerely,

Haim Melman.

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# US PATENT & TRADEMARK OFFICE

## PATENT APPLICATION FULL TEXT AND IMAGE DATABASE



( 4 of 5 )

**United States Patent Application****20010018236****Kind Code****A1****Badehi, Avner Pierre****August 30, 2001**

Methods for producing packaged integrated circuit devices & packaged integrated circuit devices produced thereby

### Abstract

This invention discloses a crystalline substrate based device including a crystalline substrate having formed thereon a microstructure; and at least one packaging layer which is sealed over the microstructure by means of an adhesive and defines therewith at least one gap between the crystalline substrate and the at least one packaging layer. A method of producing a crystalline substrate based device is also disclosed.

Inventors: **Badehi, Avner Pierre; (Harei Yehuda, IL)**  
Correspondence Name and Address: **ROYLANCE, ABRAMS, BERRO & GOODMAN, L.L.P.  
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US**

Assignee Name and Address: **Shellcase Ltd.**

Serial No.: **725166**

Series Code: **09**

Filed: **November 29, 2000**

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**U.S. Current Class:****438/127; 438/106; 438/118****Intern'l Class:****H01L 021/44; H01L 021/48; H01L 021/50**

### Foreign Application Data

**Date**  
Dec 12, 1999

**Code**  
IL

**Application Number**  
133453

### Claims



( 1 of 3 )

United States Patent  
*Melman*

6,134,393  
October 17, 2000

Imaging device for standard camera bodies

### Abstract

An imaging device for fitting to a standard camera body is provided. The device includes an imaging die mounted on a support element and a glass cover attached to the upper surface of the die. The imaging device is located along the optical axis of the camera body.

Inventors: **Melman; Haim Zvi** (Kfar Saba, IL)  
Assignee: **Scitex Corporation Ltd.** (Herzlia, IL)  
Appl. No.: **925343**  
Filed: **September 8, 1997**

### Foreign Application Priority Data

Sep 09, 1996[IL]

119227

**Current U.S. Class:**

**396/429; 348/64**

**Intern'l Class:**

**G03B 017/24**

**Field of Search:**

**396/429,374,439,535,536,538 257/621 348/64**

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357/621.

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257/621.

264/261.